

	! " #	\$! % & ' ! () % * +
--	-------	------------------------

BR2N7002K2Q

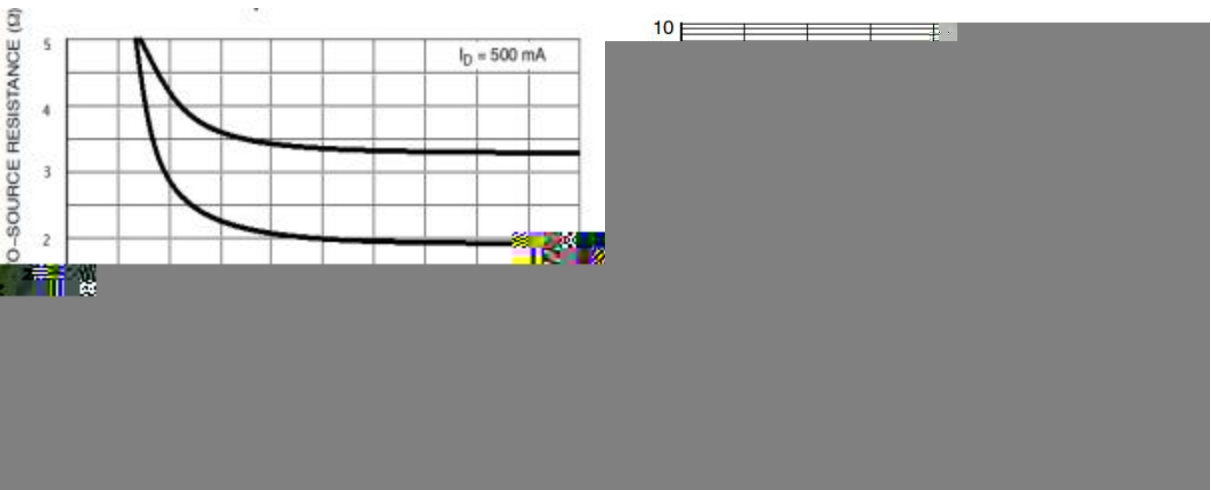
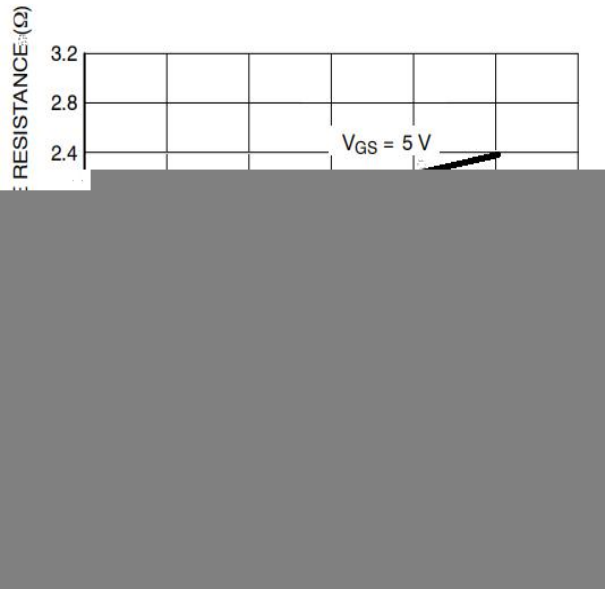
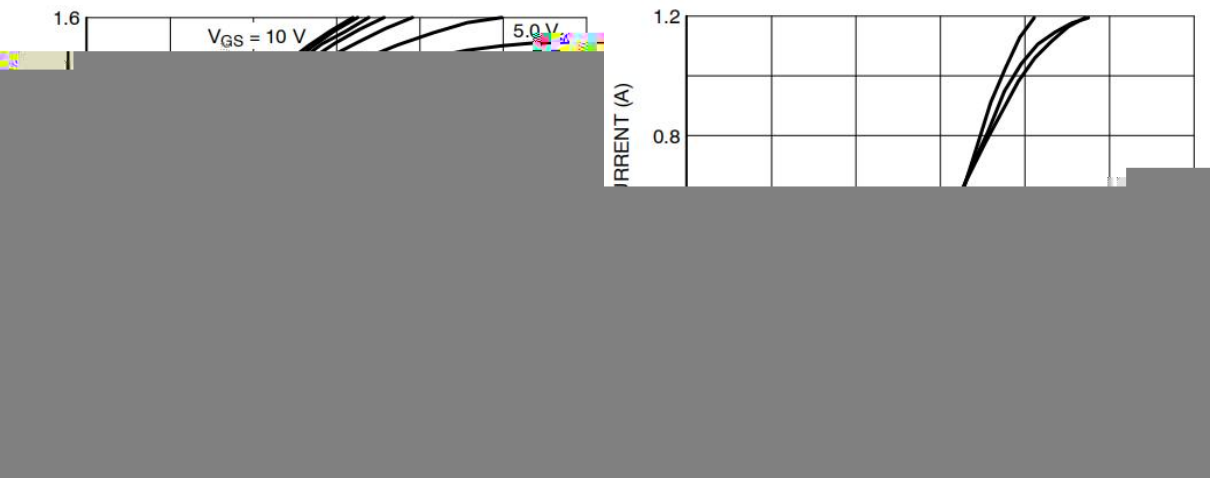
Rev.C Jul.-2022



DATA SHEET

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(ON)}$			12.2		
Rise Time	t	VGS =10V, VDD=25V, ID=500mA, RG=25 Ω				ns

/ Electrical Characteristic Curve



BR2N7002K2Q

BR2N7002K2Q

Rev.C Jul.-2022

DATA SHEET

BR2N7002K2Q

Rev.C Jul.-2022



DATA SHEET

B



R

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

- 说明：
- 1、预热温度 150 ~ 200 , 时间 60 ~ 120sec;

2、峰值温度 255 5 , 时间持续 5 ~ 0.5sec;

3、焊接制程冷却速度为 2 ~ 1 /sec.
- 1.Pre heating:150~200 , Time:60~120sec.

2.Peak Temp.:255 5 , Duration:5 ~ 0.5sec.

3.Cooling Speed:2~1 /sec.

/ Resistance to Soldering Heat Test Conditions

温度：260 5